

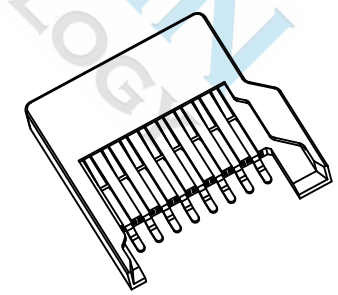
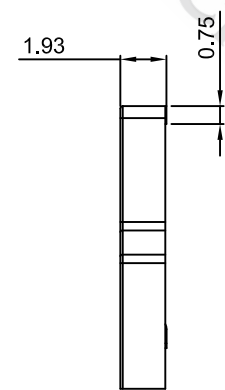
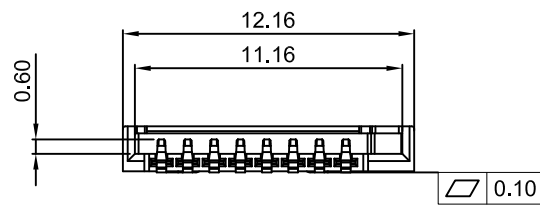
RECOMMENDED PCB LAYOUT

MATERIALS

- HOUSING: HI-TEMP. PLASTIC (UL 94V-0)
- SOLDER PAD: COPPER ALLOY, TIN PLATING
- TERMINAL: COPPER ALLOY, GOLD PLATED ON CONTACT AREA
TIN PLATING ON SOLDER TAIL

SPECIFICATION

- CURRENT RATING: 0.5 AMP MAX
- DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE
- CONTACT RESISTANCE: 50m OHMS MAX
- INSULATION RESISTANCE: 500M OHMS MIN AT DC 500V
- OPERATION TEMPERATURE: -20°C~+85°C



Pin No.	NAME	TYPE	DESCRIPTION
1	DAT 2	I/O/PP	Date Line(bit2)
2	CD/DAT 3	I/O/PP	Card Detect/Date Line(bit3)
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Colck
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Date Line(bit0)
8	DAT1	I/O/PP	Date Line(bit1)

DIMENSIONS TOLERANCE METRIC	UNITS	MM	FINISH	SEE NOTE	CH'K	Calvin	DRAW NAME MICRO SD ALL PLASTIC SMT G/F NON PUSH TYPE
	Up to 5 ±0.2	QTY	N/A	DRAW	Johnson	APP'D	
Above 5~15 ±0.3	MT'L	SEE NOTE	DE'N	Mike	DATE	March .17. 2020	PART NUMBER WMSDH-8-xxRNS-S1
Above 15~30 ±0.4							DRAW NUMBER T004
Above 30~50 ±0.5							FILE NAME .DWG
Angle ±0.3°							

WISCONN Technology Co., Ltd
 Tel: +886-2-2790-1979 Fax: +886-2-2790-1569

SCALE	1/1	SIZE	A4	SHEET	1	REV.	A
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